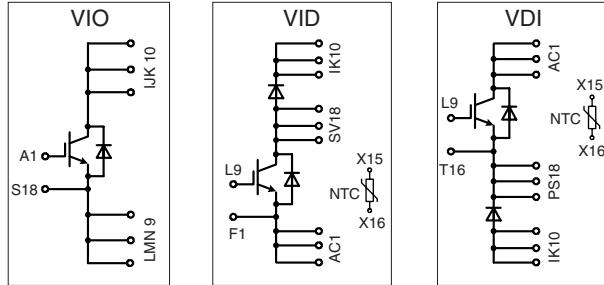


IGBT Modules in ECO-PAC 2

Short Circuit SOA Capability
Square RBSOA

I_{C25} = 169 A
 V_{CES} = 1200 V
 $V_{CE(sat)\ typ.}$ = 2.9 V



Pin arrangement see outlines

IGBTs

Symbol	Conditions	Maximum Ratings		
V_{CES}	$T_{VJ} = 25^\circ\text{C}$ to 150°C	1200	V	
V_{GES}		± 20	V	
I_{C25}	$T_C = 25^\circ\text{C}$	169	A	
I_{C80}	$T_C = 80^\circ\text{C}$	117	A	
I_{CM} V_{CEK}	$V_{GE} = \pm 15 \text{ V}$; $R_G = 6.8 \Omega$; $T_{VJ} = 125^\circ\text{C}$ RBSOA, Clamped inductive load; $L = 100 \mu\text{H}$	200	A	
t_{sc} (SCSOA)	$V_{CE} = V_{CES}$; $V_{GE} = \pm 15 \text{ V}$; $R_G = 6.8 \Omega$; $T_{VJ} = 125^\circ\text{C}$ non-repetitive	10	μs	
P_{tot}	$T_C = 25^\circ\text{C}$	694	W	

Symbol	Conditions	Characteristic Values		
		($T_{VJ} = 25^\circ\text{C}$, unless otherwise specified)		
$V_{CE(sat)}$	$I_C = 160 \text{ A}$; $V_{GE} = 15 \text{ V}$; $T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$	2.9 3.3	3.5	V
$V_{GE(th)}$	$I_C = 4 \text{ mA}$; $V_{GE} = V_{CE}$	4.5	6.5	V
I_{CES}	$V_{CE} = V_{CES}$; $V_{GE} = 0 \text{ V}$; $T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$		6 19	mA
I_{GES}	$V_{CE} = 0 \text{ V}$; $V_{GE} = \pm 20 \text{ V}$		400	nA
$t_{d(on)}$ t_r $t_{d(off)}$ t_f E_{on} E_{off}	Inductive load, $T_{VJ} = 125^\circ\text{C}$ $V_{CE} = 600 \text{ V}$; $I_C = 100 \text{ A}$ $V_{GE} = 15/0 \text{ V}$; $R_G = 6.8 \Omega$	100 60 600 90 16.1 14.6		ns ns ns ns mJ mJ
C_{ies}	$V_{CE} = 25 \text{ V}$; $V_{GE} = 0 \text{ V}$; $f = 1 \text{ MHz}$	6.5		nF
R_{thJC} R_{thJH}	(per IGBT) with heatsink compound (0.42 K/m.K; 50 μm)	0.36	0.18 K/W	K/W

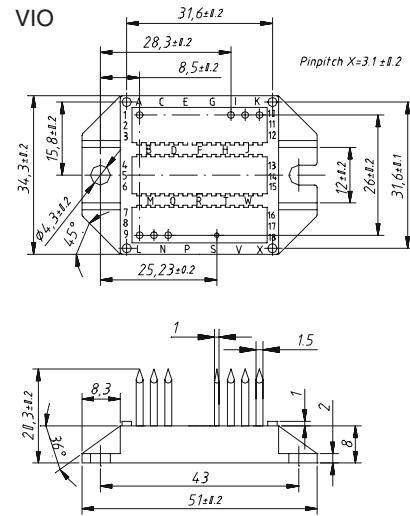
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Reverse diodes (FRED)

Symbol	Conditions	Maximum Ratings		
I _{F25}	T _C = 25°C	154	A	
I _{F80}	T _C = 80°C	97	A	

Symbol	Conditions	Characteristic Values		
		min.	typ.	max.
V _F	I _F = 100 A; T _{VJ} = 25°C T _{VJ} = 125°C	2.3 1.7	2.7 V	V
I _{RM} t _{rr}	I _F = 75 A; dI _F /dt = 750 A/μs; T _{VJ} = 125°C V _R = 600 V; V _{GE} = 0 V	79 220	A ns	
R _{thJC} R _{thJH}	with heatsink compound (0.42 K/m.K; 50 μm)	0.9	0.45 K/W K/W	

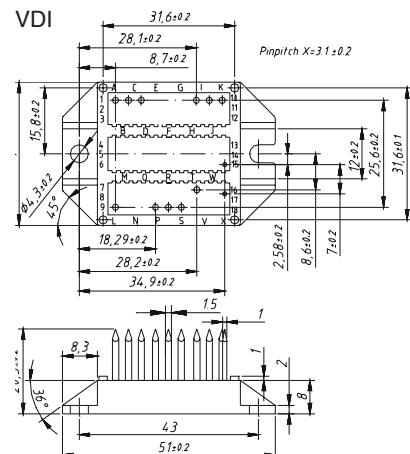


Temperature Sensor NTC

Symbol	Conditions	Characteristic Values		
		min.	typ.	max.
R ₂₅	T = 25°C	4.75	5.0	5.25 kΩ
B _{25/50}		3375		K

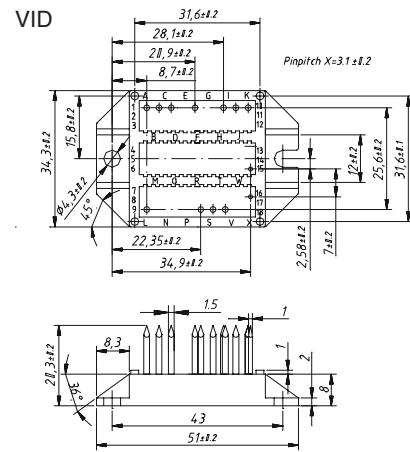
Module

Symbol	Conditions	Maximum Ratings		
T _{VJ}		-40...+150	°C	
T _{stg}		-40...+150	°C	
V _{ISOL}	I _{ISOL} ≤ 1 mA; 50/60 Hz	3000	V~	
M _d	mounting torque (M4)	1.5 - 2.0 14 - 18	Nm lb.in.	
a	Max. allowable acceleration	50	m/s ²	



Symbol	Conditions	Characteristic Values		
		min.	typ.	max.
d _s	Creepage distance on surface (Pin to heatsink)	11.2		mm
d _A	Strike distance in air (Pin to heatsink)	11.2		mm
Weight		24		g

Data according to IEC 60747 and refer to a single transistor or diode unless otherwise stated.



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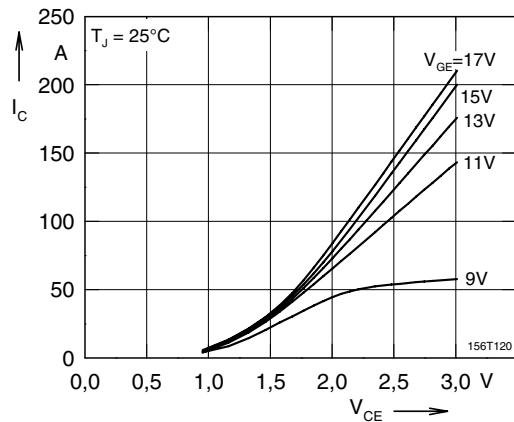


Fig. 1 Typ. output characteristics

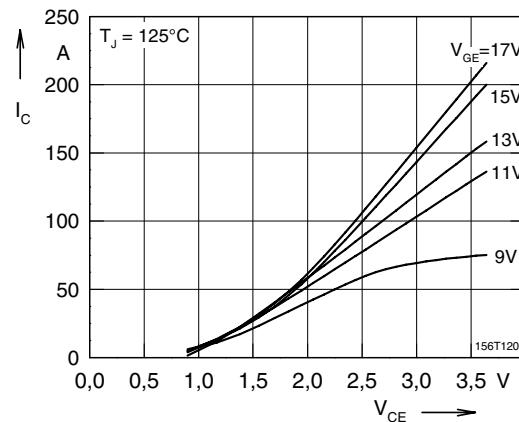


Fig. 2 Typ. output characteristics

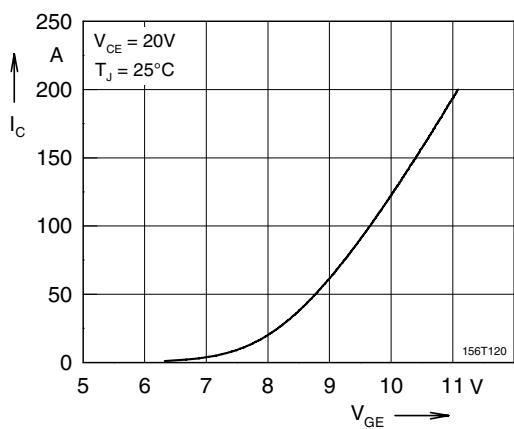


Fig. 3 Typ. transfer characteristics

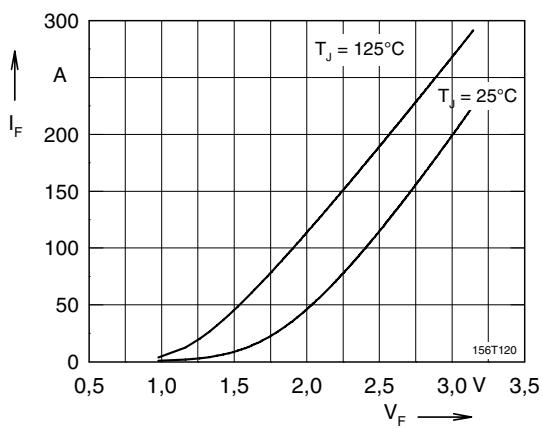


Fig. 4 Typ. forward characteristics of free wheeling diode

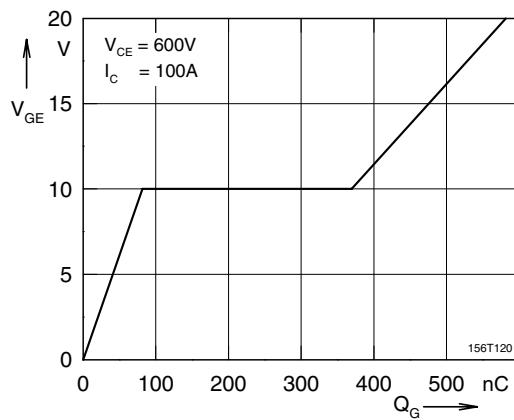


Fig. 5 Typ. turn on gate charge

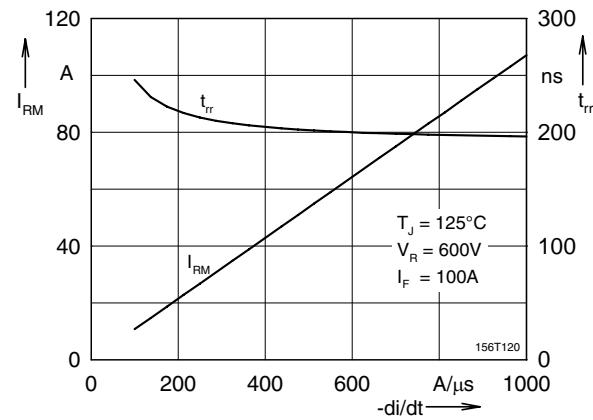


Fig. 6 Typ. turn off characteristics of free wheeling diode

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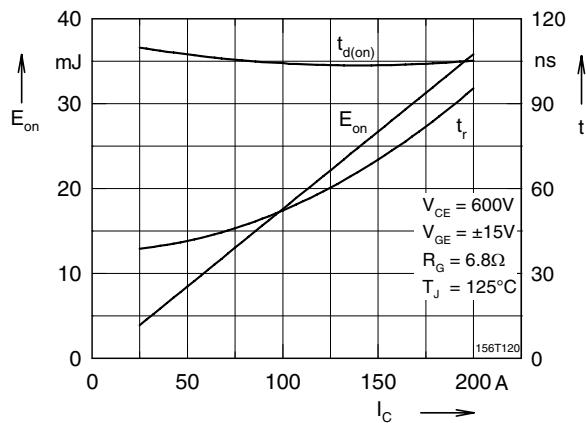


Fig. 7 Typ. turn on energy and switching times versus collector current

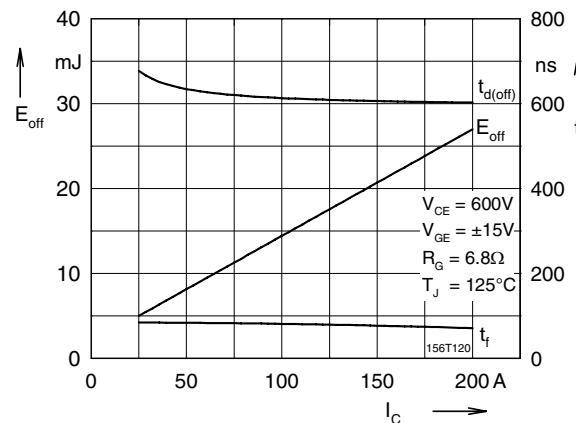


Fig. 8 Typ. turn off energy and switching times versus collector current

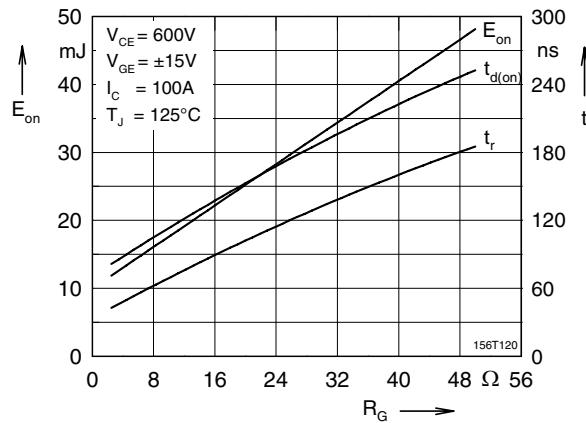


Fig. 9 Typ. turn on energy and switching times versus gate resistor

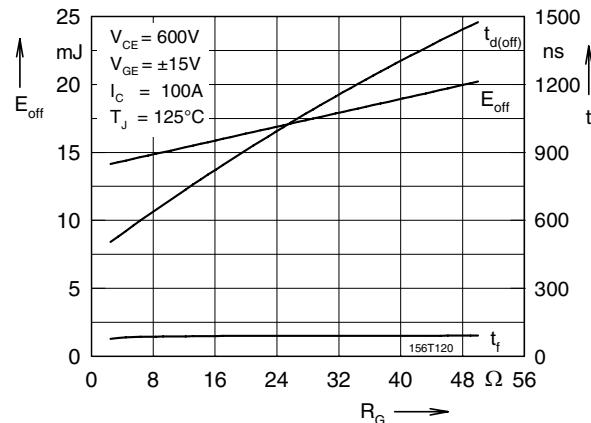


Fig.10 Typ. turn off energy and switching times versus gate resistor

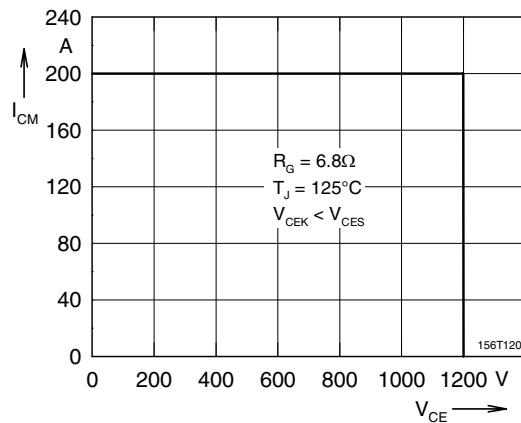


Fig. 11 Reverse biased safe operating area RBSOA

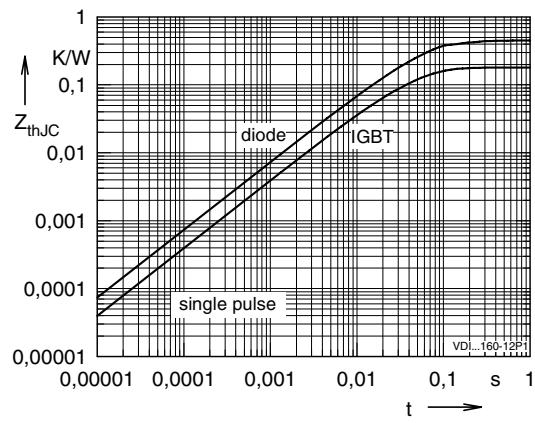


Fig. 12 Typ. transient thermal impedance